

IMPACT 2021

Oct. 20-22 Taipei, Taiwan



Call for Papers

**Accepted Papers Will Be
Collected in IEEE Xplore!**

IMPACT 2021 Conference, organized by IEEE-EPS-Taipei, IMAPS-Taiwan, ITRI and TPCA, is the largest gathering of PCB and packaging professionals in Taiwan. This year will be held on Oct. 20th -22nd at Taipei Nangang Exhibition Center, in conjunction with TPCA Show 2021. For grasping the latest trend, the symposium this year highlights the theme "IMPACT on 5G+". As the rapid growth of 5G coverage over the world, the 5G commercial network enables an array of revolutionary technologies such as IoT, artificial intelligence (AI), edge computing and wearable devices. Given the foundational infrastructure is advancing along with technologies, 5G brings faster speed and connectivity to those using it.

IMPACT 2021 looks at the cutting-edge technological applications. With the increasing amount of data collected and leverage machine learning and artificial intelligence, may achieve a breakthrough in terms of high security and privacy-preservation, and increased efficiency.

IMPACT 2021 will arrange plenary speeches, special sessions, industrial sessions, invited talks, and outstanding paper and poster presentations. Meanwhile, this conference keeps collaborating with international organizations such as ICEP、JIEP from Japan, KAIST from South Korea, and INEMI from USA in this year's gathering.

【Date】: Oct 20 (Wed)-22(Fri), 2021
【Venue】: Taipei Nangang Exhibition Center
【Theme】: IMPACT on 5G+

【Exhibition】: TPCA Show、TAITRONICS、Laser & Photonics Taiwan、OPTO TAIWAN、AIoT Taiwan
【On-line Submission】: www.impact.org.tw

IMPORTANT DATE

Item	Date	Remark
Abstract Submission Deadline (Camera-ready Version)	June 18	400-500 words, 1-2 pages Submit on-line www.impact.org.tw
Abstract Acceptance Notification	July 14	Notice sent via email
Advanced Program Online	August 18	Advanced program announcement
Full Paper Submission (Camera-ready Version)	August 31	4 pages including figures and tables. Submitting on-line through conference website with IEEE copyright forms

SCOPE OF PAPER SOLICITED

Packaging	PCB
P1. Advanced Packaging Technologies	B1. Advanced and Green Materials and Process
P2. Power Electronics Packaging	B2. Test, Quality, AOI, Inspection and Reliability
P3. Heterogeneous Integration	B3. HDI Technology(Fine and ultra fine line technology for Rigid、Flex、Rigid/Flex and IC substrate)
P4. Wearable Technologies	B4. Electroplating and Electrochemical Processing Technology
P5. Interconnections & Nanotechnology	B5. Smart Manufacturing and Automation
P6. Modeling, Simulation & Design	
P7. Thermal Management	
P8. Advanced Sensor & Microsystems Technology (MST)	
P9. Advanced Materials, Automatic Process & Assembly	
P10. Emerging Systems Packaging Technologies	

- * Papers relevant with the above scopes are encouraged to submit but NOT limited to.
- * Conference authority keeps the right to finalize session arrangement.
- * Authors of accepted papers including oral presentation and posters should register before the deadline; please be noted that un-registered (paid) papers will be removed from the symposium program.
- * The secretariat reserves the right to modify the agenda.

PAPER AWARD

Outstanding Paper Award will be elected by IMPACT Technical Program Committee from student and industrial papers respectively. The paper awardees will be announced and honored next year.

SPONSOR

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CONTACT WINDOW

IMPACT 2021 Secretariat:
Taiwan Printed Circuit Association (TPCA)
Tel: +886-3-3815659
#407 Cindy #404 Sophia #406 Vivi
Fax: +886-3-3815150
Email: service@impact.org.tw
<http://www.impact.org.tw>



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